

## Features

- Frequency range : 20MHz to 66MHz
- Ultra compact and thin
- AuSn sealing, ceramic SMD package
- External dimensions (mm)  
L : 1.6 x W : 1.2 x H : 0.35
- RoHS compliant & Pb free

## Applications

- BT, BLE, W-LAN, NFC
- SiP modules
- Mobile phone, Wearables
- Internet of Things (IoT)
- Portable consumer products

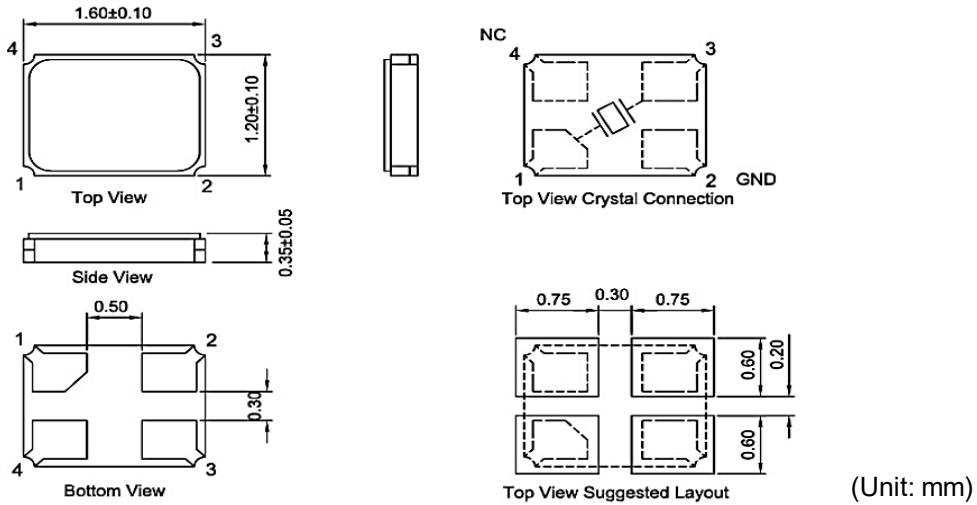
## Electrical Characteristics

Item		8Q	Conditions
Frequency Range	$F_0$	20MHz ~ 66MHz	
Frequency Tolerance	$F_{tol}$	$\pm 30\text{ppm}$ , $\pm 20\text{ppm}$ , $\pm 10\text{ppm}$	at 25°C
Frequency Stability over Operating Temperature Range (refer to 25°C)	$F_{stab}$	$\pm 30\text{ ppm}$	-20°C ~ +70°C
		$\pm 20\text{ ppm}$	
		$\pm 10\text{ ppm}$	
		$\pm 10\text{ ppm}$	-30°C ~ +85°C
		$\pm 30\text{ ppm}$	-40°C ~ +85°C
		$\pm 20\text{ ppm}$	
Operating Temperature Range	$T_{OTR}$	-20°C ~ +70°C	
		-40°C ~ +85°C	
		-40°C ~ +125°C	
Shunt Capacitance	$C_0$	3pF Max.	
Drive Level	$D_L$	1 ~ 200 $\mu$ W (50 $\mu$ W Typ.)	
Load Capacitance	$C_L$	6pF, 7pF, 8pF, 9pF, 10pF, 12pF, 16pF, 18pF	
Aging	$F_{aging}$	$\pm 3\text{ ppm Max.}$	at 25°C $\pm$ 3°C, first year
Storage Temperature Range	$T_{STR}$	-55°C ~ +125°C	

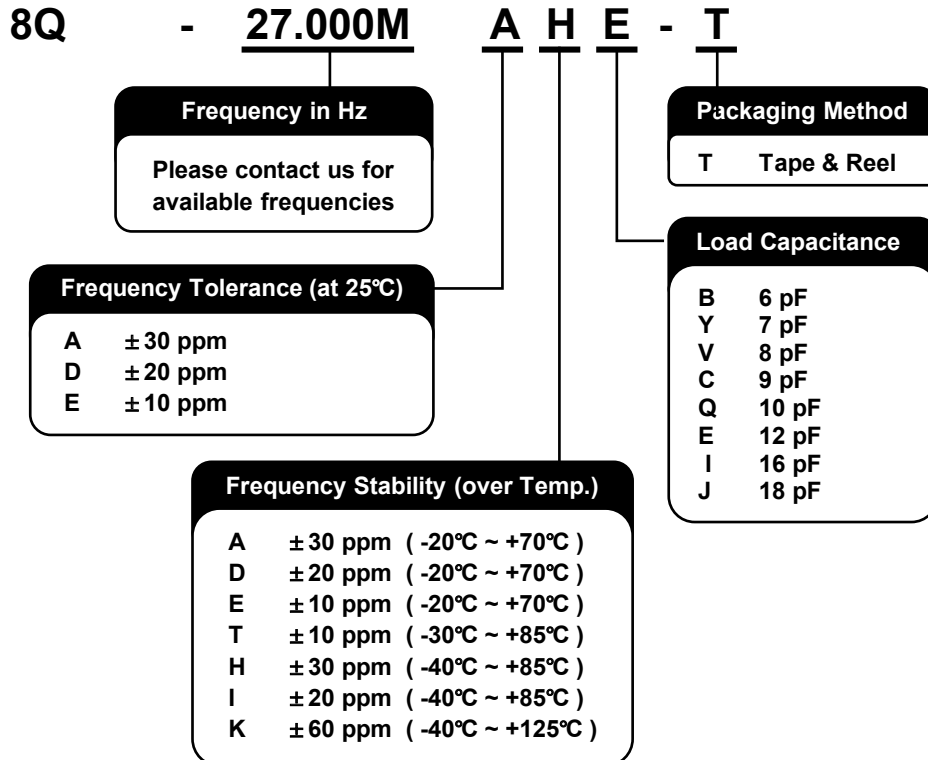
## Motional Resistance (ESR)

Fundamental	
20 ~ 30 MHz	100 $\Omega$ Max.
30 ~ 66 MHz	80 $\Omega$ Max.

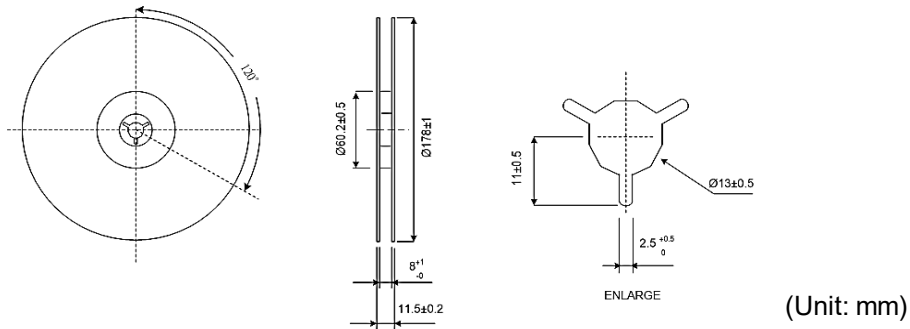
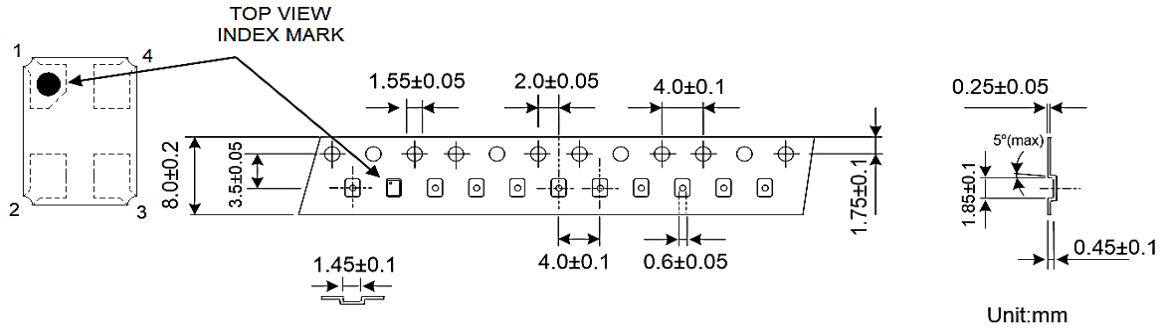
### Dimensions



### Ordering Information



### Packing



### Reflow Profile

Solder melting point : 220°C ± 10°C, 60 sec. Min.

Peak temperature : 260°C ± 10°C, 10 sec. Min.

